

FlipChip International's *EDC*[™] Enables Embedded Die Packaging

PHOENIX, ARIZONA November 13th, 2007—FlipChip International today announced the introduction of its new *EDC*[™], Embeddable Die Customization[™] technology targeted at readying integrated circuits and other devices for integration into emerging 3D packaging solutions. *EDC*[™] enables the embedding of semiconductor devices within printed circuit boards or other interconnection schemes thereby enabling lower profile, more reliable packaging schemes for applications including next generation cell phones.

The versatility of FCI's *EDC*[™] technology supports the integration of most emerging embedded die technologies whether based on laser via, photo-via or plasma etched via build up technologies. Additionally, the combination of FCI's *EDC*[™] technology and widely accepted thin film redistribution building blocks enables cost-effective component I/O pitch reduction, and inherent loosening of bare die component placement requirements. This feature addresses one of the major technological hurdles to embedded die packaging schemes and provides practical alternatives for overall process simplification and cost reduction.

Ted Tessier, Chief Technical Officer of FlipChip International, said, "Recent interest in 3D packaging technologies by our customers has been overwhelming. In particular, interest in embedded die technologies is fueling the emergence of a robust infrastructure to support the anticipated adoption of 3D packaging solutions in handheld communication and semiconductor packaging applications within the next 2 to 3 years. The launch of *our EDC*[™] service provides the industry with a standardized format for embeddable components that will dramatically enable this emerging packaging option. *EDC*[™] is the first in a series of 3D based technologies that FCI is developing in our FABLAB facilities located at FCI-1 in Phoenix, Arizona. With our targeted development and growing FABLAB capabilities, FCI is committed to lead the industry in 3D Wafer Level packaging solutions in the same way that we have led the way in the commercialization of flip chip and Wafer Level Chip Scale Packaging technologies over the past decade".

FlipChip International, LLC is a privately held supplier of products and services for the wafer bumping and wafer scale packaging semiconductor market. Flip Chip International, LLC is a wholly owned subsidiary of RoseStreet Labs LLC, a supplier of products and services for the semiconductor services, renewable energy markets and life sciences.

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